504294998 03/29/2017

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT4341679

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Chia-Chen Wu	03/28/2017
Pin-Hong Chen	03/28/2017
Kai-Jiun Chang	03/28/2017
I-An Huang	03/28/2017
Chih-Chieh Tsai	03/28/2017
Tzu-Chieh Chen	03/28/2017
Tsun-Min Cheng	03/28/2017
Yi-Wei Chen	03/28/2017

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN
Name:	FUJIAN JINHUA INTEGRATED CIRCUIT CO., LTD.
Street Address:	6TH FLOOR, PODIUM OF ELECTRIC POWER COMPANY BUILDING, MEILING STREET, JINJIANG CITY
City:	QUANZHOU CITY, FUJIAN PROVINCE
State/Country:	CHINA

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15472308

CORRESPONDENCE DATA

Fax Number: (703)997-4517

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 3027291562

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Correspondent Name: WINSTON HSU

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Address Line 4: NEW TAIPEI CITY, TAIWAN

PATENT

504294998 REEL: 041772 FRAME: 0567

ATTORNEY DOCKET NUMBER:	NAUP2963USA
NAME OF SUBMITTER:	SIBYL YU
SIGNATURE:	/SIBYL YU/
DATE SIGNED:	03/29/2017
Total Attachments: 16	
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PATENT REEL: 041772 FRAME: 0568

Title of Invention: METHOD FOR FABRICATING SEMICONDUCTOR DEVICE

As the below named inventor, I herek This declaration is directed to:	by declare that:			
☑ The attached application, or				
☐ United States application nur	mber	filed	on	, or
☐ PCT international application	number	file	ed on	
The above-identified application was	made or authorized	to be made by me.		
I believe that I am the original inventorapplication.	or or an original joint	inventor of a claime	ed invention in	the
I hereby acknowledge that any willfulunder18 U.S.C. 1001 by fine or impri	l false statement ma sonment of not mor	de in this declaration e than five (5) years	n is punishable , or both.	e
In consideration of the payment by	UNITED MICRO CORP.	ELECTRONICS	having a po 	stal address of
No.3, Li-Hsin Road 2, Science	-Based Industria	al Park, Hsin-Chu	ı City 300, 1	Taiwan, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, and for other good are in consideration of the payment by	nd valuable consider Fujian Jinhua Ir	e Dollar (\$ 1.00), the ration. ntegrated Circuit		ch is hereby
	Co., Ltd.			-
6th floor, Podium of electric p Quanzhou City, Fujian provin	oower company ce 362200, P.R.(building, Meiling C.	street, Jinj	iang city,
(referred to as "ASSIGNEE"below) t acknowledged, andfor other good at	o I of the sum of On nd valuable conside	e Dollar (\$ 1.00), the ration.	e receipt of wh	ich is hereby
I hereby sell, assign and transfer to the entire right, title and interest in a invention as above-identified applica- invention by the above application of substitutes, or extensions thereof, a	nd to any and all im ation and, in and to, or any continuations,	provements which a all Letters Patent to continuation-in-part	re disclosed ir be obtained fo , divisions, rer	n the or said newals,
I hereby covenant that no assignme entered into which would conflict with	nt, sale, agreement th this assignment;	or encumbrance has	s been or will	be made or
I further covenant that ASSIGNEE vand documents relating to said inveknown and accessible to I and will trelated thereto and will promptly except the said in the	ntion and said Lette estify as to the same	rs Patent and legal e e in any interference	equivalents as , litigation pro	may be

Page 1 of 16

F#NPO-P0002E-US1201

maintain, is equivalents	tives any and all papers, instrume ssue and enforce said application s thereof which may be necessary	, said invention and sa , or desirable to carry o	id Letters Patent and so out the proposes thereo	aid of.
IN WINTNE	ESS WHEREOF, I have hereunto	set hand and seal this	MAR 2 8 2017	(Date of signing)
Note: An a inventive e	pplication data sheet (PTO/SB/14 ntity, must accompany this form.	or equivalent), includi Use this form for <u>each</u>	ng naming the entire additional inventor.	
LEGAL NA	ME OF INVENTOR(ASSIGNOR)			
Inventor:	Chia-Chen Wu	Date:	MAR 2 8 2017	
Signature:	Chia-c	Chia-Chen	Wu	

Page 2 of 16

NPO#NAU-P2963-USA:0 CUST#UMCF-2016-0155

Title of Invention: METHOD FOR FABRICATING SEMICONDUCTOR DEVICE

As the below named inventor, I here This declaration is directed to:	by declare that:			
☑ The attached application, or				
☐ United States application number		filed c	on	, or
☐ PCT international application number		file	d on	
The above-identified application was	made or authorize	ed to be made by me.		
I believe that I am the original invent application.	or or an original joi	nt inventor of a claime	d invention in the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr				
In consideration of the payment by	UNITED MICRO	DELECTRONICS	having a postal ad	dress of
No.3, Li-Hsin Road 2, Science	-Based Industr	ial Park, Hsin-Chu	City 300, Taiwa	n, R.O.C
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar			receipt of which is h	ereby
In consideration of the payment by	Fujian Jinhua Co., Ltd.	Integrated Circuit	having a postal ad	dress of
6th floor, Podium of electric p Quanzhou City, Fujian provin	oower company ce 362200, P.R.	building, Meiling C.	street, Jinjiang o	ity,
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good are			receipt of which is h	ereby
I hereby sell, assign and transfer to the entire right, title and interest in a invention as above-identified applica- invention by the above application o substitutes, or extensions thereof, a	nd to any and all in ition and, in and to r any continuations	nprovements which are , all Letters Patent to b , continuation-in-part,	e disclosed in the e obtained for said divisions, renewals,	
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Page 3 of 16

F#NPO-P0002E-US1201 DSB0-106U000605

PATENT REEL: 041772 FRAME: 0571

Signature:	PM-Hong Chen			
Inventor:	Pin-Hong Chen	Date:	MAR 2 8 2017	
LEGAL NA	ME OF INVENTOR(ASSIGNOR)			
	ntity, must accompany this form. Use this			
Note: An a	pplication data sheet (PTO/SB/14 or equiv	ralent), including	naming the entire	
equivalents	ssue and enforce said application, said inv s thereof which may be necessary or desir ESS WHEREOF, I have hereunto set hand	able to carry ou		of.
•	tives any and an papers, instruments of an	•		

Page 4 of 16

Title of Invention: METHOD FOR FABRICATING SEMICONDUCTOR DEVICE

As the below named inventor, I here This declaration is directed to:	by declare that:			
☑ The attached application, or				
☐ United States application nu	☐ United States application numberfiled		on	, or
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The above-identified application was	made or authorized	d to be made by me.		
I believe that I am the original invent application.	or or an original join	t inventor of a claime	d invention in the	
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In consideration of the payment by	UNITED MICRO	ELECTRONICS	having a postal add	dress of
No.3, Li-Hsin Road 2, Science	e-Based Industri	al Park, Hsin-Chu	City 300, Taiwar	ı, R.O.C.
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I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica- invention by the above application o substitutes, or extensions thereof, an	nd to any and all im ition and, in and to, r any continuations,	provements which are all Letters Patent to b continuation-in-part,	e disclosed in the e obtained for said divisions, renewals,	
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement h this assignment;	or encumbrance has	been or will be made	e or
I further covenant that ASSIGNEE wand documents relating to said inverknown and accessible to I and will to related thereto and will promptly exercise.	ntion and said Letter estify as to the same	s Patent and legal ed in any interference,	uivalents as may be litigation proceeding	cts

Page 5 of 16

NPO#NAU-P2963-USA:0 CUST#UMCF-2016-0155

representatives any and all papers, instruments or afficient maintain, issue and enforce said application, said invent equivalents thereof which may be necessary or desirable	tion and said	Letters Pater	nt and sa	
IN WINTNESS WHEREOF, I have hereunto set hand a		MAR 28		(Date of signing)
Note: An application data sheet (PTO/SB/14 or equivale inventive entity, must accompany this form. Use this form				
LEGAL NAME OF INVENTOR(ASSIGNOR)				
Inventor: Kai-Jiun Chang	Date:	MAR 2	8 2017	-
Signature: Kai-Tian Chang	g tropic services and services a			

Page 6 of 16

Title of Invention: METHOD FOR FABRICATING SEMICONDUCTOR DEVICE

As the below named inventor, I here This declaration is directed to:	by declare that:			
☑ The attached application, or				
☐ United States application number		file	d on	, or
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The above-identified application was	made or autho	rized to be made by m	e.	
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6th floor, Podium of electric բ Quanzhou City, Fujian provin	oower compa ce 362200, P	nny building, Meilir .R.C.	ng street, Jinjiang c	ity,
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I hereby sell, assign and transfer to the entire right, title and interest in a invention as above-identified applica- invention by the above application o substitutes, or extensions thereof, a	nd to any and a ation and, in and r any continuati	Il improvements which I to, all Letters Patent t ons, continuation-in-pa	are disclosed in the to be obtained for said art, divisions, renewals,	IEE
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Page 7 of 16

F#NPO-P0002E-US1201 DSB0-106U000605

REEL: 041772 FRAME: 0575

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	pplication data sheet (PTO/SB/14 or equival ntity, must accompany this form. Use this fo			
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LEGAL NA	ME OF INVENTOR(ASSIGNOR)			
Inventor:	I-An Huang	Date:	MAR 2 8 2017	***************************************
Signature:	I-An Huang			related from the control of the cont

Page 8 of 16

NPO#NAU-P2963-USA:0 CUST#UMĆF-2016-0155

Title of Invention: METHOD FOR FABRICATING SEMICONDUCTOR DEVICE

As the below named inventor, I herel This declaration is directed to:	by declare that:			
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Page 9 of 16

NPO#NAU-P2963-USA:0 CUST#UMCF-2016-0155

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	pplication data sheet (PTO/SB/14 on ntity, must accompany this form. U			
I EGAL NA	ME OF INVENTOR(ASSIGNOR)			
LLOAL IVA	WE OF HAVEIATOR (AGGIGNOR)			
Inventor:	Chih-Chieh Tsai	Date:	MAR 2 8 2017	
Signature:	Chih - Chiah	Teai		

Page 10 of 16

NPO#NAU-P2963-USA:0 CUST#UMCF-2016-0155

Title of Invention: METHOD FOR FABRICATING SEMICONDUCTOR DEVICE

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☐ United States application nul	mber	filed	on	or
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The above-identified application was	made or authoriz	ed to be made by me.		
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In consideration of the payment by	UNITED MICR CORP.	OELECTRONICS	having a postal add	ress of
No.3, Li-Hsin Road 2, Science	-Based Industi	rial Park, Hsin-Ch	u City 300, Taiwan	, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	o I of the sum of O d valuable consid	ne Dollar (\$ 1.00), the eration.	e receipt of which is he	reby
In consideration of the payment by	Fujian Jinhua Co., Ltd.	Integrated Circuit	having a postal add	ress of
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I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified applica invention by the above application of substitutes, or extensions thereof, ar	nd to any and all ir tion and, in and to rany continuations	nprovements which a , all Letters Patent to s, continuation-in-part	re disclosed in the be obtained for said , divisions, renewals,	EE
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Page 11 of 16

NPO#NAU-P2963-USA:0 CUST#UMCF-2016-0155

maintain, issue and enforce equivalents thereof which ma	said application, said inv	ention and said	d Letters Patent and s	
IN WINTNESS WHEREOF,			MAR 28 2017	
Note: An application data shinventive entity, must accom				
LEGAL NAME OF INVENTO		Date:	1442	
TZu-Chieff C	ien	Date.	MAR 2 8 2017	
Signature: Tzu - (hieh Chen			

Page 12 of 16

NPO#NAU-P2963-USA:0 CUST#UMCF-2016-0155

Title of Invention:

METHOD FOR FABRICATING SEMICONDUCTOR DEVICE

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☐ United States application nu	mber	filed on,	or
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No.3, Li-Hsin Road 2, Science	-Based Industrial Park, Hsi	n-Chu City 300, Taiwan,	R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	o I of the sum of One Dollar (\$ 1.0 d valuable consideration.	0), the receipt of which is here	eby
In consideration of the payment by	Fujian Jinhua Integrated C Co., Ltd.	ircuit having a postal addre	ess of
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I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified applica invention by the above application or substitutes, or extensions thereof, an	nd to any and all improvements w tion and, in and to, all Letters Pat any continuations, continuation-i	hich are disclosed in the ent to be obtained for said n-part, divisions, renewals,	Έ
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Page 13 of 16

NPO#NAU-P2963-USA:0 CUST#UMCF-2016-0155

representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof. IN WINTNESS WHEREOF, I have hereunto set hand and seal this MAR 2 8 2017 (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

Tsun-Min Cheng

MAR 2 8 2017

Signature:

Page 14 of

F#NPO-P0002E-US1201

Title of Invention: METHOD FOR FABRICATING SEMICONDUCTOR DEVICE

As the below named inventor, I here This declaration is directed to:	by declare that:			
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Page 15 of 16

NPO#NAU-P2963-USA:0 CUST#UMCF-2016-0155

Signature:	Yi-Wei	don	Ti-Wei (then	***
Inventor:	Yi-Wei Chen		Date:	MAR 2 8 2017	
LEGAL NA	ME OF INVENTOR(AS	SIGNOR)	s.		
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IN WINTNE	ESS WHEREOF, I have	hereunto set h	and and seal this	MAR 28 2017	(Date of signing)
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Page 16 of 16

NPO#NAU-P2963-USA:0 CUST#UMCF-2016-0155 F#NPO-P0002E-US1201 DSB0-106U000605

PATENT REEL: 041772 FRAME: 0584

RECORDED: 03/29/2017